

AMENDED CLAIMS

1. (Canceled)
2. (Currently amended) An LED device according to ~~claim 1~~,
comprising:
a light emitting semiconductor;
a cover over said semiconductor and spaced apart therefrom; and
a phosphor layer contained within or coated on an inside or outer surface
of said cover, wherein said inside surface of said cover has a surface area at
least ten times the exposed surface area of the light emitting semiconductor.
3. (Currently amended) An LED device according to ~~claim 1~~
claim 2, further comprising a transparent filler positioned between said light
emitting semiconductor and said cover.
4. (Original) An LED device according to claim 3, wherein said
transparent filler is an optical coupling material which may be an epoxy, silicone,
acrylic, thermoplastic, urethane, polyimide or an index modified matching fluid or
gel.
5. (Previously presented) An LED device according to claim 4,
wherein said filler has a refractive index closely matching the geometric mean of
the refractive index of said light emitting semiconductor and said cover material.
6. (Currently amended) An LED device according to ~~claim 1~~
claim 2, wherein said phosphor layer has a substantially uniform thickness.
7. (Currently amended) An LED device according to ~~claim 1~~
claim 2, wherein said phosphor layer is formed from a slurry comprising one or
more phosphors and a binder.

8. (Currently amended) An LED device according to ~~claim—4~~
claim 2, wherein said phosphor layer is formed from a slurry comprising one or more phosphors, a scattering medium and a binder.

9. (Original) An LED device according to claim 7, wherein said slurry may contain a carrier solvent and said binder is a transparent refractive index matching material.

10. (Original) An LED device according to claim 9, wherein said solvent is methyl ethyl ketone and said binder is selected from the group consisting of silicone, acrylic, epoxy, thermoplastic and polyimide.

11. (Currently amended) An LED device according to ~~claim—4~~
claim 2, wherein said phosphor layer comprises one or more of $Y_3Al_5O_{12}:Ce$, $Tb_3Al_4.9O_{12}:Ce$, $Sr_4Al_{14}O_{25}:Eu$, and mixtures thereof.

12. (Currently amended) An LED device according to ~~claim—4~~
claim 2, wherein said light emitting semiconductor is a blue emitting LED or a UV emitting LED having a primary emission in the range of 200–480 nm.

13. (Currently amended) An LED device according to ~~claim—4~~
claim 2, wherein said LED device emits white light.

14. (Currently amended) An LED device according to ~~claim—4~~
claim 2, having a package efficiency of 70% or greater.

15. (Currently amended) An LED device according to ~~claim—4~~
claim 2, wherein said lens comprises a sphere or hemisphere and said light emitting semiconductor is positioned at the center of said sphere or hemisphere.

16. (Previously presented) An LED device comprising:
a light emitting semiconductor;

a cover over said semiconductor and positioned apart from the light emitting semiconductor by a distance at least about two times the length of a longest side of said light emitting semiconductor; and

a phosphor layer contained within or coated on an inside or outer surface of said cover.

17. (Canceled)

18. (Currently amended) An LED device according to ~~claim 17~~ claim 23, further comprising a reflective layer positioned between said phosphor layer and said reflector.

19. (Original) An LED device according to claim 18, wherein said reflective layer comprises a high dielectric powder.

20. (Currently amended) An LED device according to ~~claim 17~~ claim 23, further comprising a submount on which said semiconductor is mounted, wherein said submount is also coated with said phosphor layer.

21. (Currently amended) An LED device according to ~~claim 17~~ claim 23, wherein said phosphor layer is from 6 to 100 μm thick.

22. (Currently amended) An LED device according to ~~claim 17~~ claim 23, wherein said semiconductor is a blue or UV emitting LED in the range of 200-480 nm.

23. (Currently amended) An LED device according to ~~claim 17~~, comprising:

a light emitting semiconductor;

a reflector supporting said light emitting semiconductor;

a cover over said semiconductor and said reflector and spaced apart from said semiconductor; and

a uniform thickness phosphor layer coated on at least a portion of said reflector and contained within or coated on an inside or outer surface of said

cover, the light emitting semiconductor, reflector, cover, and phosphor layer defining an LED device having a package efficiency of 70% or greater.

24. (Currently amended) An LED device according to claim 17 claim 23, wherein said LED chip is free of said phosphor coating.

25. (Currently amended) A method for forming an LED device having a cover with a uniform phosphor coating, said method comprising the steps of:

providing an LED mounted on a support;

providing a cover sized to fit over or around said support;

depositing a uniform thickness phosphor coating on a surface of said cover; and

~~assembling~~ assembling said LED, mount and lens to form said LED device.

26. (Previously presented) A method according to claim 25, wherein said step of depositing said phosphor on said cover comprises the substeps of:

forming a slurry comprising phosphor powder, a solvent and a binder;

optionally heating said cover to a temperature above room temperature;

stamping, screening, dispensing, rolling, brushing or spraying said slurry onto said lens to achieve a uniform thickness coating layer; and

curing said binder to form a permanent coating layer.

27-30. (Canceled).

31. (Currently amended) An LED device comprising:
a plurality of light emitting semiconductors mounted on a reflective electrical interconnect board;

a cover over said semiconductors and spaced apart from said semiconductors; and

a phosphor layer contained within or coated on an inside or outer surface of said cover, wherein the phosphor layer has an area greater than about ten times an exposed surface area of the light emitting semiconductor.

32. (Previously presented) An LED device according to claim 31 in which said cover has a refractive index matching a refractive index of said light emitting semiconductors for improved light extraction and chip protection

33. (Previously presented) A LED device according to claim 31, wherein said plurality of light emitting semiconductors comprise blue LEDs, said device further comprising a band pass light filter positioned on said cover between the phosphor layer and said blue LEDs, said band pass filter functioning to pass the emission wavelength of the LEDs and reflect the emission wavelength of the phosphor layer.

34. (Previously presented) A LED device according to claim 31, wherein said plurality of light emitting semiconductors comprise UV LEDs, said device further comprising a first band pass light filter positioned on said cover between the phosphor layer and said blue LEDs, for passing the emission wavelength of the LEDs and reflecting the emission wavelength of the phosphor layer, and a second band pass light filter positioned on an exterior surface of said cover for passing the emission wavelength of the phosphors and reflecting the emission wavelength of the LEDs.

35. (Previously presented) A LED device according to claim 31 in which an array of micro or macro lenses is formed on the outer surface of the cover to control the emission angle, direction or intensity of the emitted radiation.

36. (Previously presented) A LED device according to claim 31 in which the cover is easily detachable from said LED device such that additional covers containing different phosphor mixes or amounts can be installed to easily adjust the light color temperature, CIE and CRI without changing the light emitting

semiconductors.